

Thin Film Power Chip Terminator



YOKOHAMA DENSHI SEIKO Co., Ltd.

2.5W (1608) ~100W (9464) DC to 10GHz

<AlN Substrate>

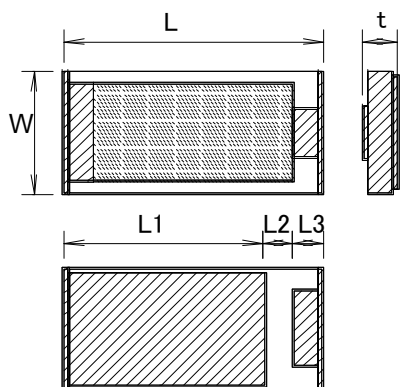
RoHS
Compliance

<Specification>

| Type | HPT1608 | HPT2012 | HPT3216 | HPT5025 | HPT6432 | HPT6464 | HPT9464 | HPT9464H |
|---------------------|-----------------------------|------------------------------|-----------------------------|-----------------------------|-----------------------------|-----------------------------|-----------------------------|-----------------------------|
| Size | 1.6 x 0.8 x 0.4mm (0603) | 2.0 x 1.25 x 0.4mm (0805) | 3.2 x 1.6 x 0.4mm (1206) | 5.0 x 2.5 x 0.4mm (2010) | 6.4 x 3.2 x 0.6mm (2512) | 6.3 x 6.3 x 0.6mm (2525) | 9.4 x 6.3 x 0.6mm (3725) | 9.4 x 6.3 x 0.6mm (3725) |
| Power | 2.5W | 5W | 10W | 20W | 30W | 60W | 80W | 100W |
| VSWR | DC ~ 3GHz | 1.2 | 1.2 | 1.2 | 1.3 | 1.3 | 1.3 | 1.3 |
| | 3.1 ~ 5GHz | 1.2 | 1.3 | 1.3 | 1.5 | 1.5 | | |
| | 5.1 ~ 7.5GHz | 1.3 | 1.3 | 1.4 | | | --- | --- |
| | 7.6 ~ 10GHz | 1.3 | 1.4 | 1.5 | --- | --- | --- | --- |
| | 10.1 ~ 12.5GHz | 1.4 | 1.5 | --- | --- | --- | --- | --- |
| 12.6 ~ 15GHz | 1.5 | --- | --- | --- | --- | --- | --- | |
| Operating Temp. | -40°C ~ +155°C | | | | | | | |
| Rated Ambient Temp. | +80°C | | | | | | | |

Notes. While this component is fully powered, make sure the soldered surface temperature does not exceed +80°C.

<Dimensions>

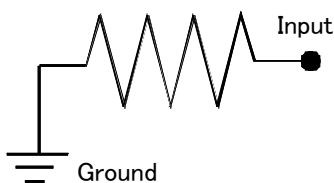


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|------|----------|-----------|----------|----------|----------|-----------|-----------|-----------|
| L | 1.6±0.15 | 2.0±0.15 | 3.2±0.2 | 5.0±0.2 | 6.4±0.2 | 6.3±0.2 | 9.4±0.2 | 9.4±0.2 |
| W | 0.8±0.15 | 1.25±0.15 | 1.6±0.2 | 2.5±0.2 | 3.2±0.2 | 6.3±0.2 | 6.3±0.2 | 6.3±0.2 |
| L1 | 1.1±0.15 | 1.5±0.15 | 2.7±0.2 | 3.6±0.2 | 5.5±0.2 | 4.9±0.2 | 7.1±0.2 | 7.1±0.2 |
| L2 | 0.3±0.15 | 0.3±0.15 | 0.3±0.15 | 0.9±0.15 | 0.7±0.15 | 0.65±0.15 | 1.15±0.15 | 1.15±0.15 |
| L3 | 0.2±0.15 | 0.2±0.15 | 0.2±0.15 | 0.5±0.15 | 0.2±0.15 | 0.75±0.15 | 1.15±0.15 | 1.15±0.15 |
| t | 0.4±0.1 | 0.4±0.1 | 0.4±0.1 | 0.65±0.1 | 0.65±0.1 | 0.65±0.1 | 0.65±0.1 | 0.65±0.1 |

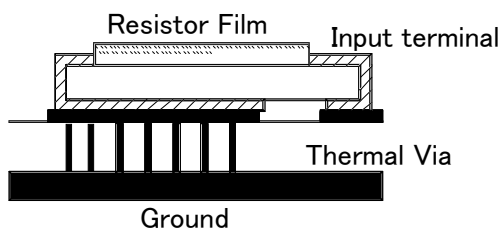
<Features>

- High power small thin film chip terminator with AlN substrate. Thin film elements and special patterning offer small size, high power and excellent high frequency performance.
- Good heat dissipation guarantees excellent ability against high power and high pulse.
- Wrap-around terminals offer easy mounting and high reliability.
- Thin film resistor has an excellent feature against stress. Impedance is stable against repeated load without accumulate fatigue.

<Equivalent circuit>



<Mounting example>



Dissipation mainly occurs from the bottom ground terminals. Please consider mounting this component on surfaces where heat dissipation is designed in, such as adding thermal via.

<Part Number>

| | | | | | |
|--------|------|---|-----------|---|--------------|
| HPT | 6464 | - | 50 | - | T1(T5) |
| Device | Size | | Impedance | | Packing form |

T1 : Taping(1,000pcs/reel)
T5 : Taping(5,000pcs/reel)



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